PCN Number:	201609130	01 PCN Date	e:	Sept.	19, 2016	
Title: Datasheet for						
Customer Contact:	PCN Manager		Dep	ot:	Quality Services	
Change Type:						
Assembly Site		Design		Wafer	· Bump Site	
Assembly Process		Data Sheet		Wafer Bump Material		
Assembly Materials		Part number change		Wafer Bump Process		
Mechanical Specification		Test Site		Wafer Fab Site		
Packing/Shipping/Labeling		Test Process		Wafer Fab Materials		
				Wafer Fab Process		
Notification Details						
Description of Change:						
Texas Instruments Incorporated is announcing an information only notification etc.						
The product datasheet(s) is being updated as summarized below.						
The following change history provides further details.						
	bry provides fi	irther details.				
Texas Instruments					THORE	
INSTRUMENTS				2015 DEV	TUSB542 ISED AUGUST 2016	
		SESENCE	DECEMBER	2013-112	13ED A00031 2010	
Changes from Revision B (January 2016) to Revision C Page						
Changed Pin 15 To: TX_AP+ and Pin 14 To: TX_AP- in the RWQ Package image						
	he datasheet number will be changing.					
Device Family			Change To:			
TUSB542		SLLSER3B		S	LSER3C	
These changes may be rev		datasheet links provided.				
http://www.ti.com/produc	<u>t/TUSB542</u>					
Reason for Change:						
To more accurately reflect device characteristics.						
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):						
No anticipated impact. This is a specification change announcement only. There are no changes to						
the actual device.						
Changes to product identification resulting from this PCN:						
None.						
Product Affected:						
TUSB542RWQR						

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com